

MATERIAL DECLARATION SHEET



| | | | | |
|-----------------|---|-----|---|--|
| Material Number | ESD Suppressing Device CDDFN2-T5.0LC | | | |
| Product Line | Semiconductor Products | | | |
| Compliance Date | 2013/8/2 | | | |
| RoHS Compliant | Yes | MSL | 3 | |

| No. | Construction Element(subpart) | Homogeneous Material | Material weight [mg] | Homogeneous Material\ Substances | CASRN if applicable | Materials Mass % | Material Mass % of total unit wt. | Subpart mass of total wt. (%) |
|--------------|-------------------------------|-----------------------|----------------------|----------------------------------|---------------------|------------------|-----------------------------------|-------------------------------|
| 1 | Wafer | Silicon | 0.05 | Silicon | 7440-21-3 | 100.00% | 4.501% | 4.501% |
| 2 | Lead frame | Copper Alloy (NiPdAu) | 0.4125 | Copper | 7440-50-8 | 93.9971% | 37.132% | 39.509% |
| | | | 0.0023 | Silicon | 7440-21-3 | 0.5196% | 0.207% | |
| | | | 0.0151 | Nickel | 7440-02-0 | 3.4298% | 1.359% | |
| | | | 0.0006 | Magnesium | 7439-95-4 | 0.1345% | 0.054% | |
| | | | 0.0004 | Iron | 7439-89-6 | 0.1003% | 0.036% | |
| | | | 0.0022 | Zinc | 7440-66-6 | 0.4991% | 0.198% | |
| | | | 0.0002 | Manganese | 7439-96-5 | 0.0501% | 0.018% | |
| | | | 0.00001 | Lead | 7439-92-1 | 0.0023% | 0.001% | |
| | | Nickel plating | 0.0051 | Nickel | 7440-02-0 | 1.1509% | 0.459% | |
| | | Palladium plating | 0.0004 | Palladium | 7440-05-3 | 0.1003% | 0.036% | |
| Gold plating | 0.0001 | Gold | 7440-57-5 | 0.0160% | 0.009% | | | |
| 3 | Epoxy | Polymer | 0.0255 | Aluminum oxide | 1344-28-1 | 50.00% | 2.296% | 4.59% |
| | | | 0.006 | Epoxy resin | Proprietary | 11.7% | 0.537% | |
| | | | 0.017 | Epoxy resin | Proprietary | 33.3% | 1.528% | |
| | | | 0.0025 | Aromatic amine | Proprietary | 5.00% | 0.229% | |

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|---|---------------|--------------|------------------|-----------------------|-------------|--------|--------|-------|
| 4 | wire | Noble metal | 0.0099 | Gold | 7440-57-5 | 99.99% | 0.891% | 0.9% |
| | | | 0.0001 | Other, not to declare | / | 0.01% | 0.009% | |
| 5 | Mold Compound | Polymer | 0.525 | Silica Fused | 60676-86-0 | 93.70% | 47.26% | 50.5% |
| | | | 0.017 | Epoxy Resin | Proprietary | 3.00% | 1.530% | |
| | | | 0.017 | Phenol Resin | Proprietary | 3.00% | 1.530% | |
| | | | 0.002 | Carbon Black | 1333-86-4 | 0.30% | 0.180% | |
| | | Total weight | 1.11091mg | | | | | |

This Document was updated on: 2015/01/13

Important remarks:

1. It is the responsibility of the user to verify they are accessing the latest version.